Product Change Notification - JAON-16HJDK892

Date: 28 Jun 2016

Product Category: Supertex

Notification subject: CCB 1715 Final Notice: Qualification of ASEW as an additional assembly site for DN2470K4 device family available in 3L DPAK package using 8060T die attach material and CEL-9240HF10AK molding compound.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of ASEW as an additional assembly site for DN2470K4 device family available in 3L DPAK package using 8060T die attach material and CEL-9240HF10AK molding compound.

Pre Change:
Assembled at GEMC using 84-1LMISR4 die attach material and EME G600 molding compound

Post Change:
Assembled at GEMC using 84-1LMISR4 die attach material and EME G600 molding compound or assembled ASEW using 8060T die attach material and CEL-9240HF10AK molding compound

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	GEMC assembly site	GEMC assembly site	ASEW assembly site
Wire material	Au wire	Au wire	Au Wire
Die attach material	84-1LMISR4	84-1LMISR4	8060T
Molding compound material	EME-G600	EME-G600	CEL-9240HF10AK
Lead frame material	PMC90	PMC90	PMC90

Impacts to Data Sheet:
None

Reason for Change:
To improve on-time delivery performance by qualifying ASEW as an additional assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
July 26, 2015 (date code: 1630)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2015				-->	June 2016					July 2016			
Workweek	32	33	34	35		22	23	24	25	26	27	28	29	30
Initial PCN Issue Date				X										
Qual Report Availability										X				
Final PCN Issue Date										X				
Estimated Implementation Date														X

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
August 26, 2015: Issued initial notification.
June 28, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from December 15, 2015 to July 26, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-16HJDK892_Qual_Report.pdf
PCN_JAON-16HJDK892_Affected_CPN.pdf
PCN_JAON-16HJDK892_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-16HJDK892
CATALOG_PART_NBR
DN2470K4-G